

Anodizing of Aluminum Covered with SiO₂ by Sol-Gel Coating - Formation mechanism of Composite Oxide Films with High Potential Sustainability -

K. WATANABE¹, M. SAKAIRI¹, H. TAKAHASHI¹,
S. HIRAI², and S. NAGATA³

¹ Graduate School of Engineering, Hokkaido University
N13, W8, Kita-ku, Sapporo, 060-8628

² Department of Materials Science and Engineering,
Muroran Institute of Technology,

Mizumoto-cho, Muroran-shi, Hokkaido 050-8585, Japan

³ Institute for Materials Research, Tohoku University,
Katahira-2, Aoba-ku, Sendai 980-8577, Japan

Introduction

During galvanostatic anodizing of aluminum in neutral electrolytic solution, a dense barrier type anodic oxide film is formed at a constant growth rate until breakdown occurs. It is of industrial significance in electrolytic capacitor manufacturing to form anodic oxide films, which can sustain voltage higher than 500V. Li et al have reported a breakdown potential over 500V during anodizing in diluted borate solutions, and the growth of anodic oxide films with many imperfections[1]. In a previous study, the authors have investigated the formation of Al-Si composite oxide films by the combination of sol-gel coating and anodizing[2].

In this investigation, the authors examined the effect of borate concentration in anodizing solution on the formation of Al-Si composite oxide films on their dielectric properties.

Experimental

Specimen: Highly pure aluminum (99.99%) foil was used as specimens (2 x 2 cm with handle) and electropolished in perchloric acid / acetic acid mixture.

Sol-gel coating : SiO₂ coating was applied to the specimen by sol-gel dip-coating. The dipping and heating at 573 K were repeated two to 5 times ($n=2\sim5$). Detail of SiO₂ sol preparation and coating process is described elsewhere. [2]

Anodizing: Specimens with / without SiO₂ film were anodized in 0.5M- H₃BO₃ (Solution-I), 0.5M-H₃BO₃ / 0.005M-Na₂B₄O₇ (Solution-II), and 0.5M-H₃BO₃ / 0.05M-Na₂B₄O₇ (Solution-III) at $T_a=333$ K with a constant current of $i_a=10$ A m⁻². Changes in the anode potential, E_a , with time, t_a were followed with a digital multi-meter connected to PC system. The amount of aluminum ions, W_{Al} , dissolved during anodizing was examined by ICP-AES.

Characterization: SiO₂ films and anodic oxide films were characterized by transmission electron microscopy (TEM), Rutherford backscattering spectroscopy (RBS), electron diffraction (ED), energy dispersive x-ray analysis (EDX), and electrochemical impedance measurement (ECI). In TEM, vertical cross sections of specimens were observed by an ultra thin sectioning technique. In ECI, specimens were immersed in a neutral borate solution at 293K, and 10mV of sinusoidal voltage was applied in the range of 10⁻²-10⁵ Hz.

Results and Discussion

Figure 1 shows the time-variations in anode potential, E_a , and the amount of dissolved Al³⁺ ions, W_{Al} , during anodizing in Solution-II at $T_a=333$ K for the specimen coated with SiO₂ at $n = 4$, and for the specimen without SiO₂. Both specimens show a linear increase in E_a with t_a until E_a reaches 550 V, and the slope of the curve for the SiO₂-coated specimen is twice as high as that for the specimen without SiO₂. The dissolution rate for SiO₂-coated specimen is lower than that for the specimen without SiO₂. The current efficiency for film formation can be estimated to be more than 99% for the SiO₂-coated specimen, assuming no gas evolution, and for the specimen without SiO₂ to be 83 %.

Figure 2 shows the TEM images of the vertical cross section of specimens a) coated with SiO₂ at $n = 4$, and b) anodized to 500 V after SiO₂-coating. An anodic oxide film grows during underneath SiO₂-coated layer during anodizing, and the thickness of the SiO₂ layer decreases. EDX and RBS measurements showed that the anodic oxide film consists of two layers: an outer Al-Si composite oxide layer and an inner pure Al₂O₃ layer. The parallel capacitance of the specimen

anodized to 500 V after SiO₂ coating was 10 % larger than that without SiO₂ coating.

The decrease in borate concentration in anodizing solution increased the film breakdown potential, and this tendency was more remarkable on SiO₂-coated specimen than on the specimen without SiO₂. The anodic oxide films formed after SiO₂ coating had a relatively small number of imperfections.

Reference

[1] Y. Li, H. Shimada, M. Sakairi, K. Shigyo, H. Takahashi, and M. Seo, *J. Electrochem. Soc.* **144** (1997) 866

[2] K. Watanabe, M. Sakairi, H. Takahashi, K. Takahiro, S. Nagata, and S. Hirai, *Submit to J. Electrochem. Soc.*

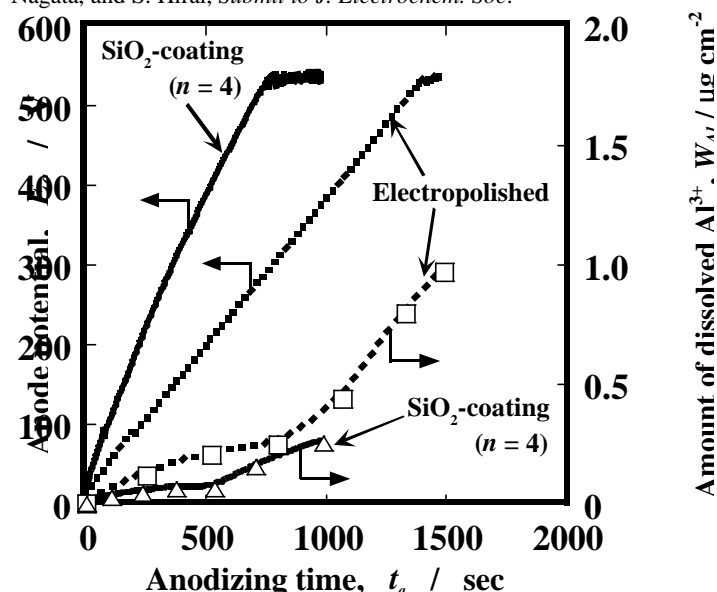


Fig. 1 Changes in anode potential, E_a , and amount of dissolved aluminum ions, W_{Al} , with time, t_a , during anodizing for electropolished and SiO₂-coated ($n = 4$) specimens.

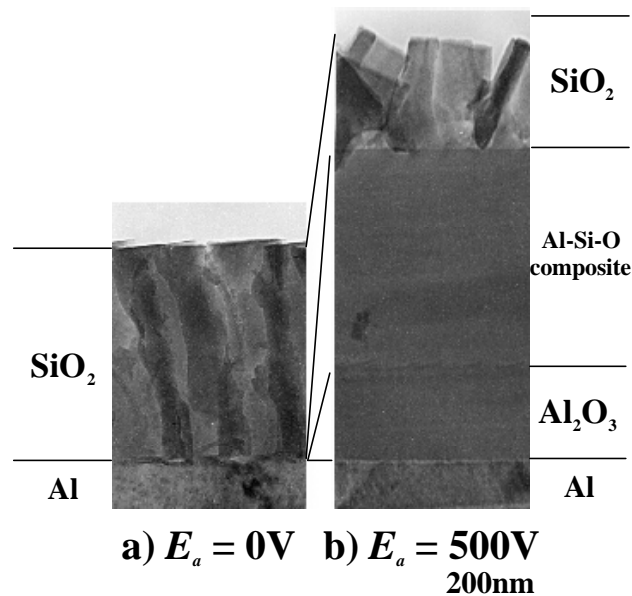


Fig. 2 TEM images of the vertical cross section of specimens a) coated with SiO₂ at $n = 4$, and b) anodized to 500V after SiO₂ coating